

[FIG 1A]
SECTIONAL VIEW, PLAN VIEW
PRODUCTION OF BAND-SHAPED CONDUCTOR
1: BOARD
5 2: CONDUCTOR PATTERN
9: FRONT/REAR ALIGNMENT THROUGH-HOLE

[FIG 1B]
LAMINATION
3: INTERLAYER ELECTRICALLY INSULATING LAYER

10 [FIG 1C]
SLICING
Y DIRECTION, X DIRECTION

[FIG 2A]
15 SECTIONAL VIEW, PLAN VIEW
FORMATION OF BRIDGING CONDUCTOR
21: BRIDGING CONDUCTOR PATTERN

[FIG 2B]
FORMATION OF PROTECTIVE LAYER
20 25: PROTECTIVE LAYER
26: VIA-HOLE

[FIG 2C]
FORMATION OF TERMINAL ELECTRODE
30: TERMINAL ELECTRODE

25 [FIG 2D]
SEPARATION INTO CHIPS

[FIG 3A]
30 SECTIONAL VIEW, PLAN VIEW
PRODUCTION OF BAND-SHAPED CONDUCTOR
1A: BOARD
2: CONDUCTOR PATTERN

[FIG 3B]
LAMINATION
35 3: INTERLAYER ELECTRICALLY INSULATING LAYER

[FIG 3C]
SLICING

[FIG 4A]
40 SECTIONAL VIEW, PLAN VIEW
FORMATION OF BRIDGING CONDUCTOR
21: BRIDGING CONDUCTOR PATTERN

[FIG 4B]

FORMATION OF PROTECTIVE LAYER
 26: VIA-HOLE
 [FIG 4C]
 FORMATION OF TERMINAL ELECTRODE
 5 30: TERMINAL ELECTRODE
 [FIG 4D]
 SEPARATION INTO CHIPS

[FIG 5A]
 10 SECTIONAL VIEW, PLAN VIEW
 PRODUCTION OF BAND-SHAPED CONDUCTOR
 1: BOARD
 2: CONDUCTOR PATTERN
 9: FRONT/REAR ALIGNMENT THROUGH-HOLE

15 [FIG 5B]
 FIRST LAMINATION
 4: INTERLAYER ELECTRICALLY INSULATING LAYER

[FIG 5C]
 SECOND LAMINATION
 20 6: ADHESIVE SHEET

[FIG 5D]
 SLICING

[FIG 6A]
 25 SECTIONAL VIEW, PLAN VIEW
 FORMATION OF BRIDGING CONDUCTOR
 21: BRIDGING CONDUCTOR PATTERN

[FIG 6B]
 FORMATION OF PROTECTIVE LAYER
 30 25: PROTECTIVE LAYER
 26: VIA-HOLE

[FIG 6C]
 FORMATION OF TERMINAL ELECTRODE
 30: TERMINAL ELECTRODE

35 [FIG 6D]
 SEPARATION INTO CHIPS

[FIG 7A]
 SECTIONAL VIEW, PLAN VIEW
 40 PRODUCTION OF BAND-SHAPED CONDUCTOR
 2: CONDUCTOR PATTERN
 7: BOARD

[FIG 7B]

ADJUSTMENT OF BOARD THICKNESS

[FIG 7C]

LAMINATION

8: ADHESIVE SHEET

5 [FIG 7D]

SLICING

8: ADHESIVE SHEET

[FIG 8A]

10 SECTIONAL VIEW, PLAN VIEW

FORMATION OF BRIDGING CONDUCTOR

21: BRIDGING CONDUCTOR PATTERN

[FIG 8B]

FORMATION OF PROTECTIVE LAYER

15 25: PROTECTIVE LAYER

26: VIA-HOLE

[FIG 8C]

FORMATION OF TERMINAL ELECTRODE

30: TERMINAL ELECTRODE

20 [FIG 8D]

SEPARATION INTO CHIPS

[FIG 9A]

PLAN VIEW (FRONT PATTERN)

25 BOTTOM VIEW (REAR PATTERN)

CORE BOARD

[FIG 9B]

CORE BOARD

[FIG 9C]

30 CORE BOARD

[FIG 10A]

SECTIONAL VIEW, PLAN VIEW

PRODUCTION OF BAND-SHAPED CONDUCTOR

35 1: ORGANIC CORE BOARD

2: CONDUCTOR PATTERN

[FIG 10B]

LAMINATION

[FIG 10C]

40 SLICING

[FIG 10D]

FORMATION OF BRIDGING CONDUCTOR

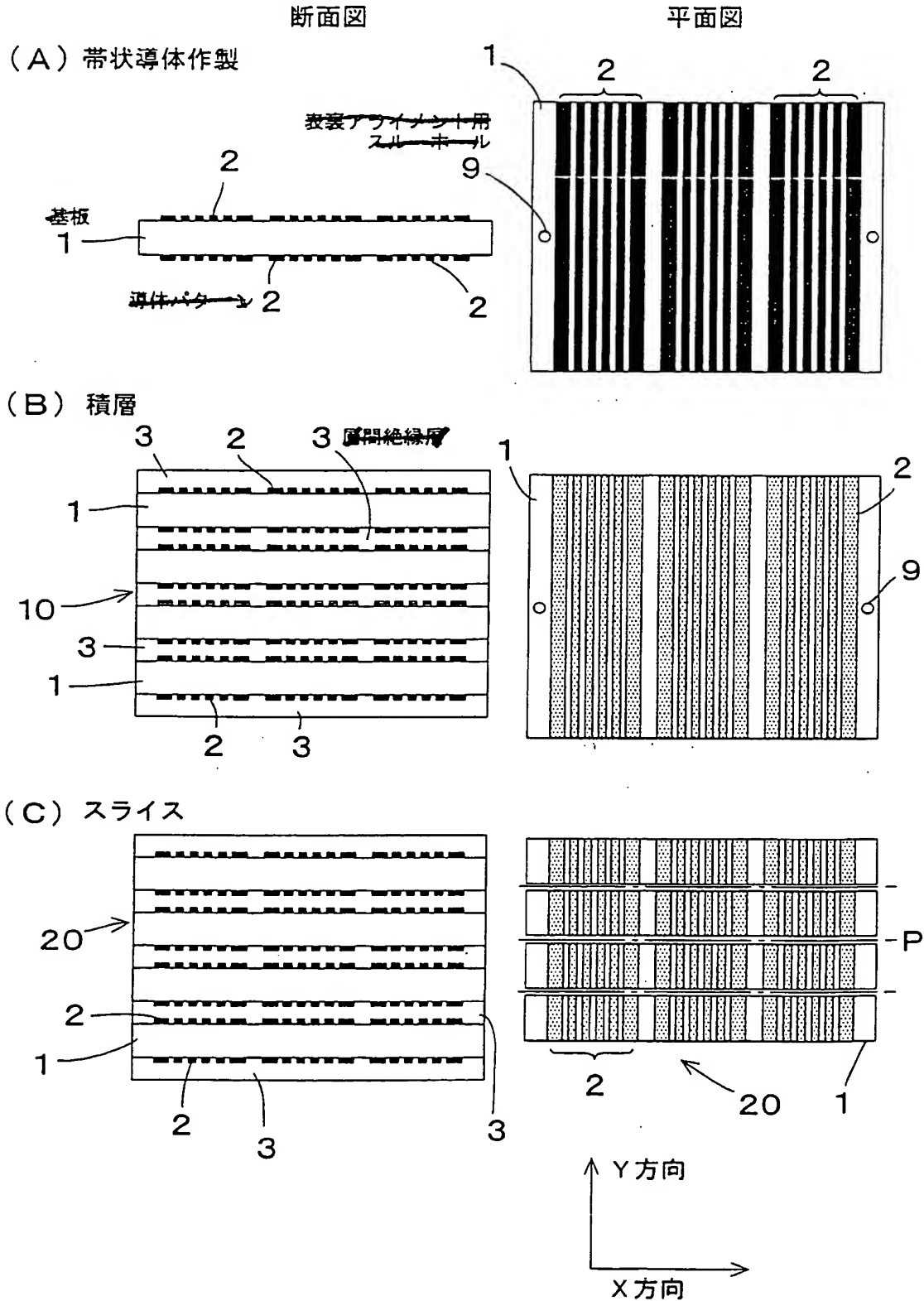
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提出日: 平成15年12月 5日

1

【書類名】 図面

【図 1】

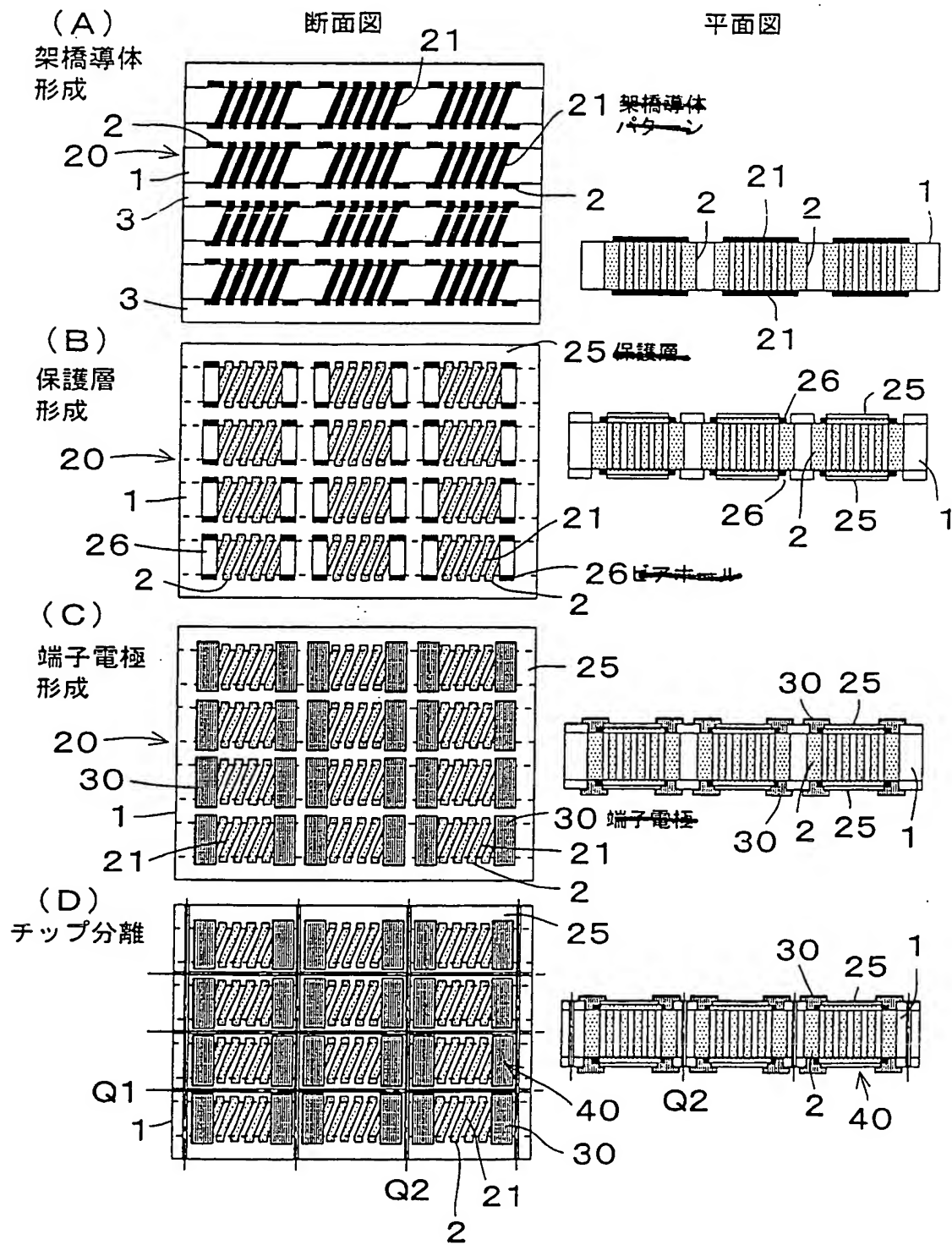


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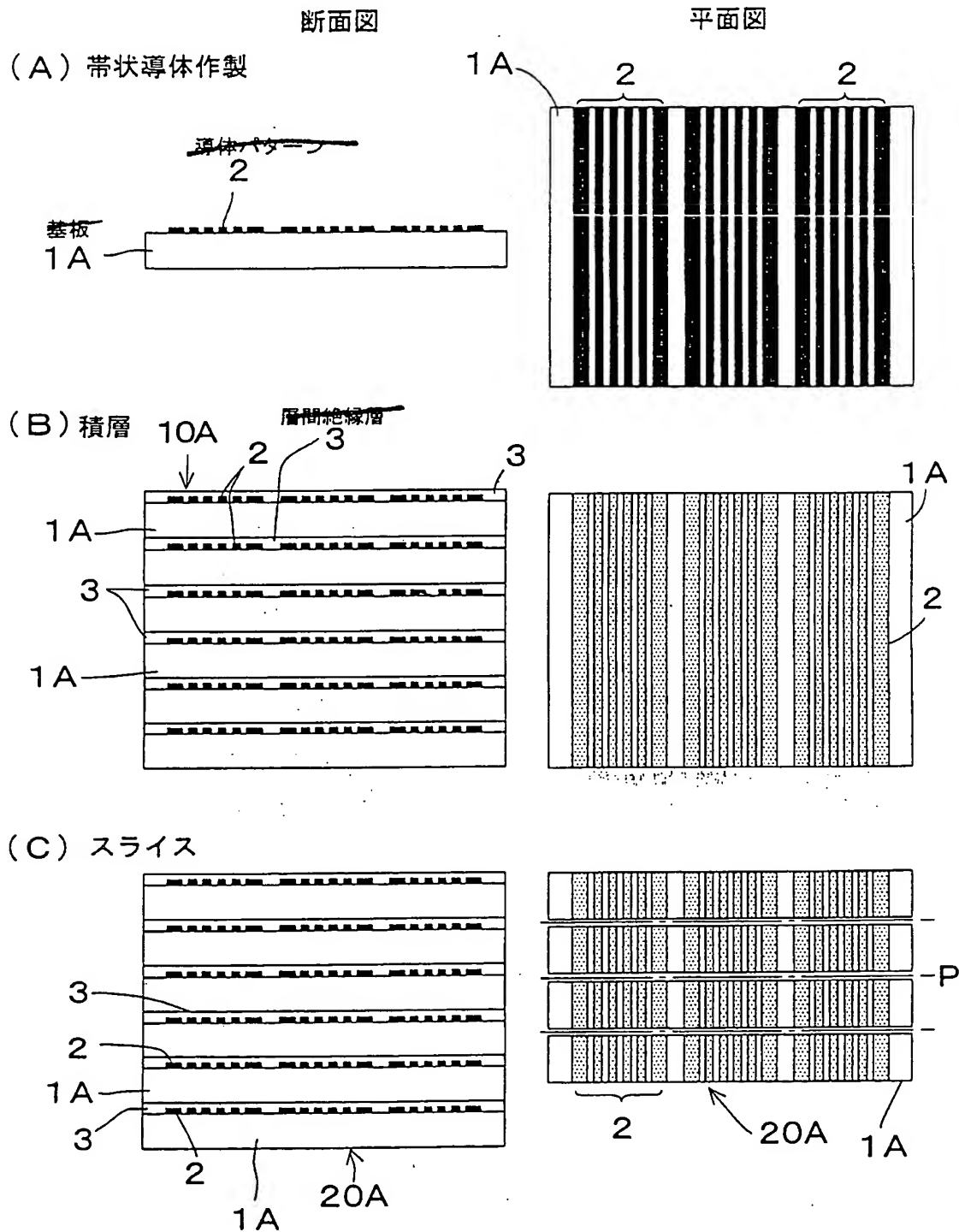
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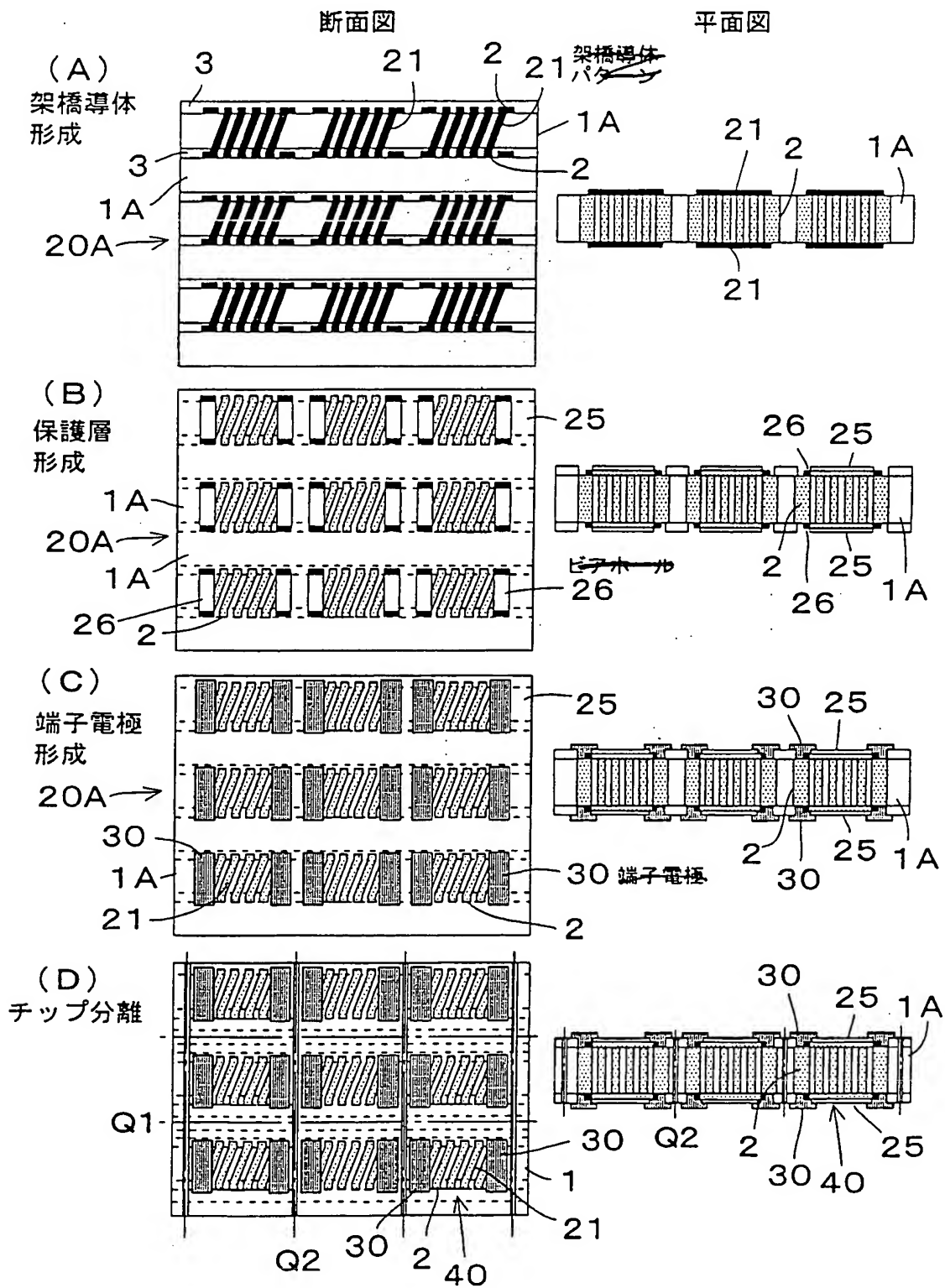
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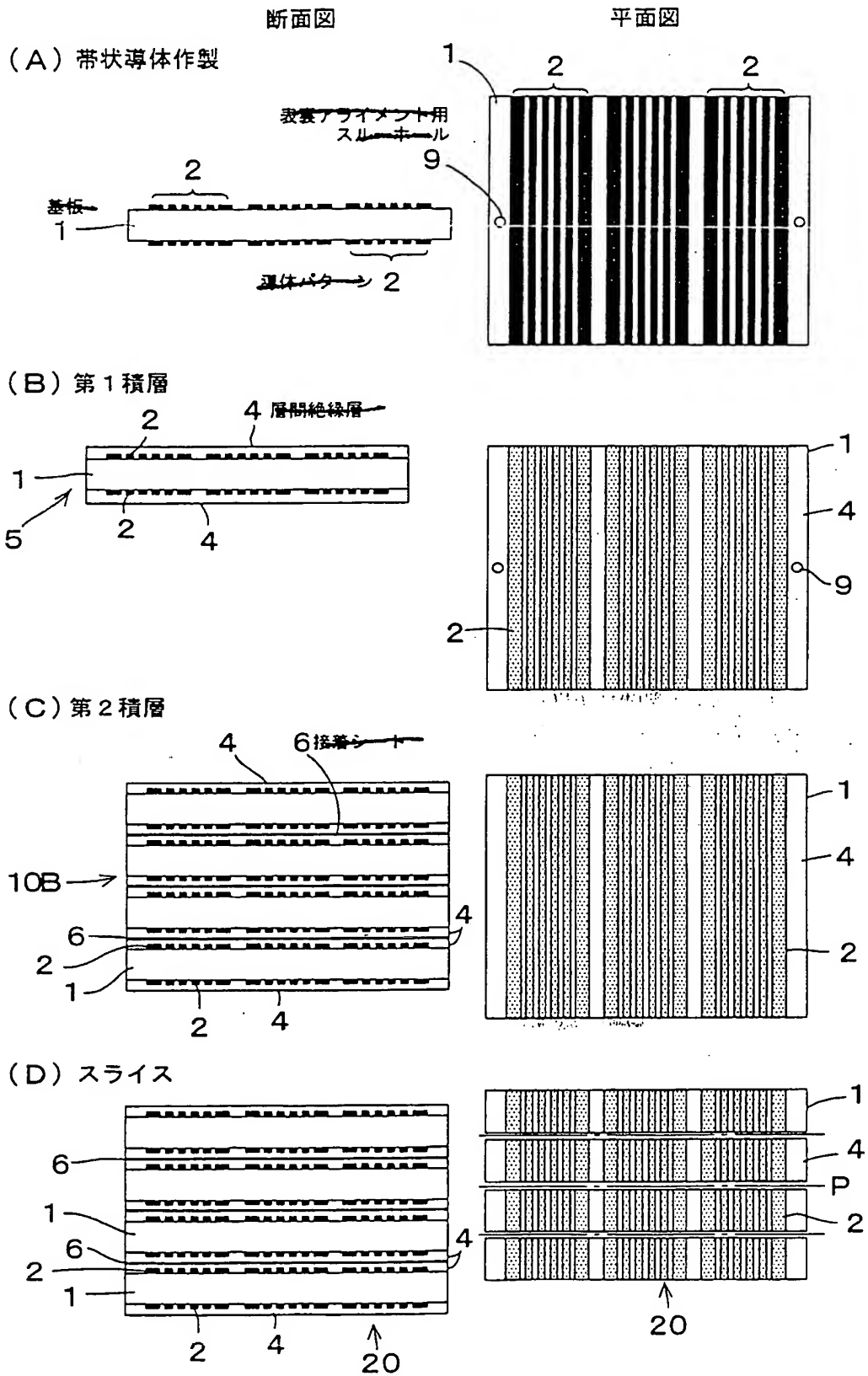
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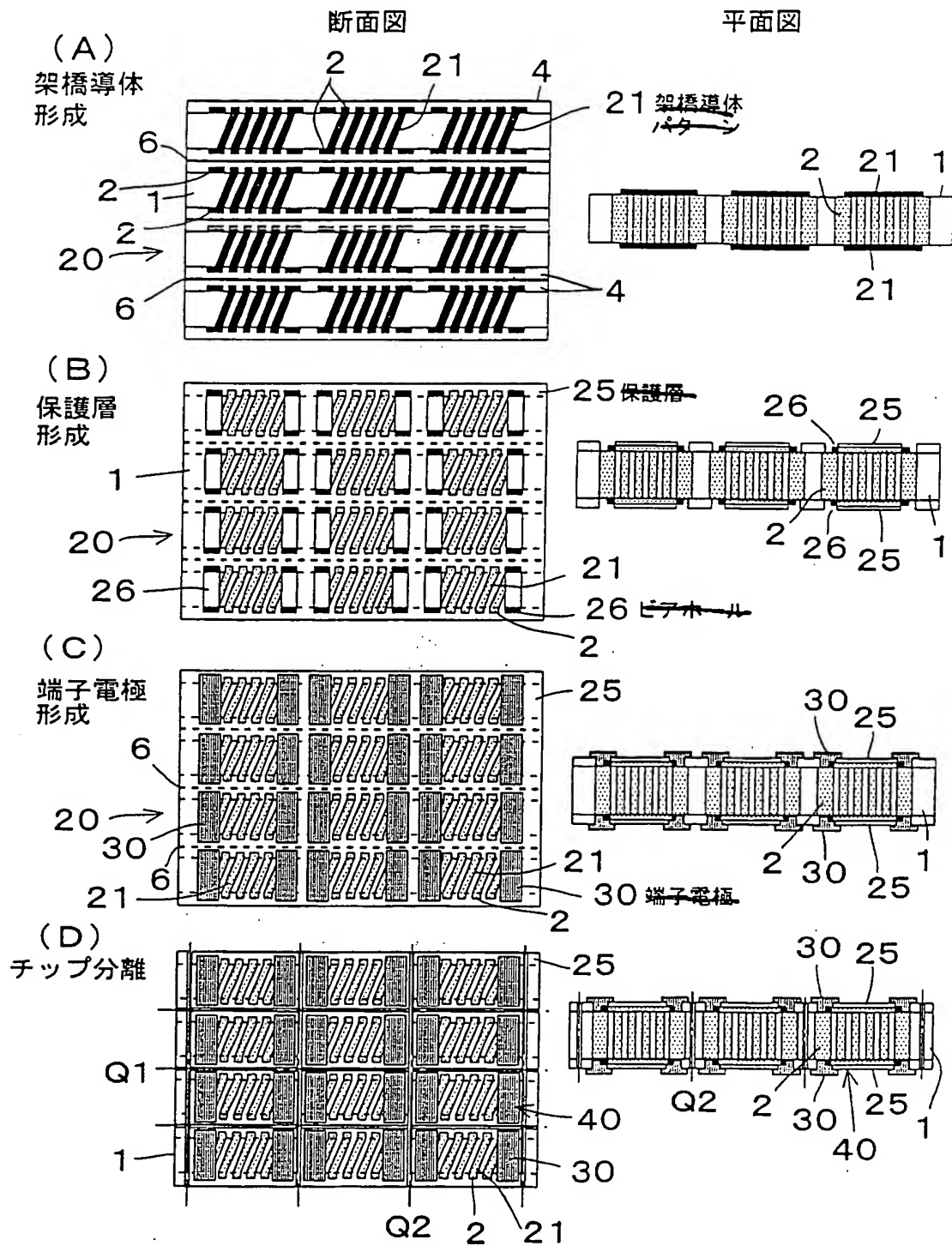
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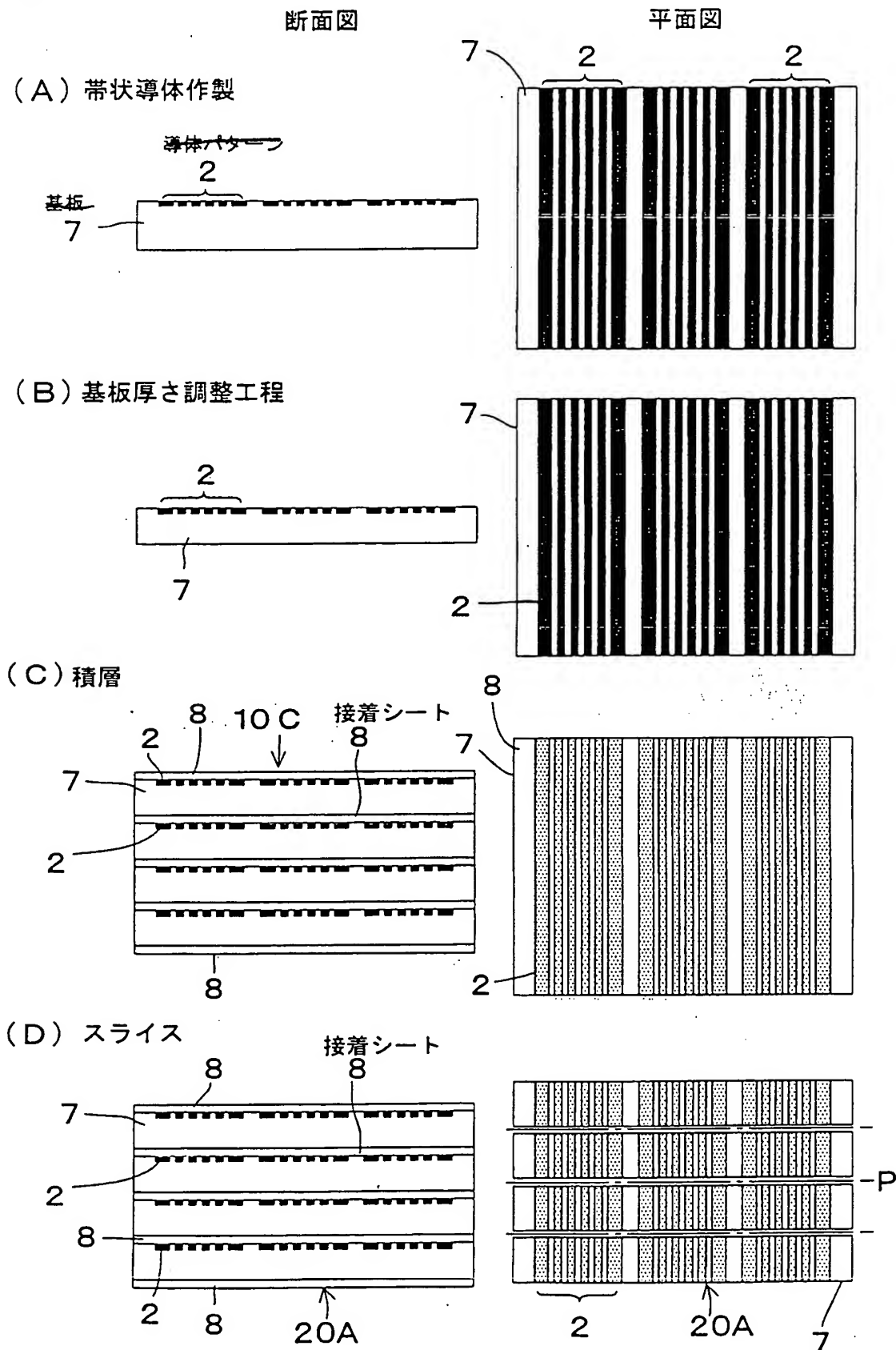
【図5】



【図6】



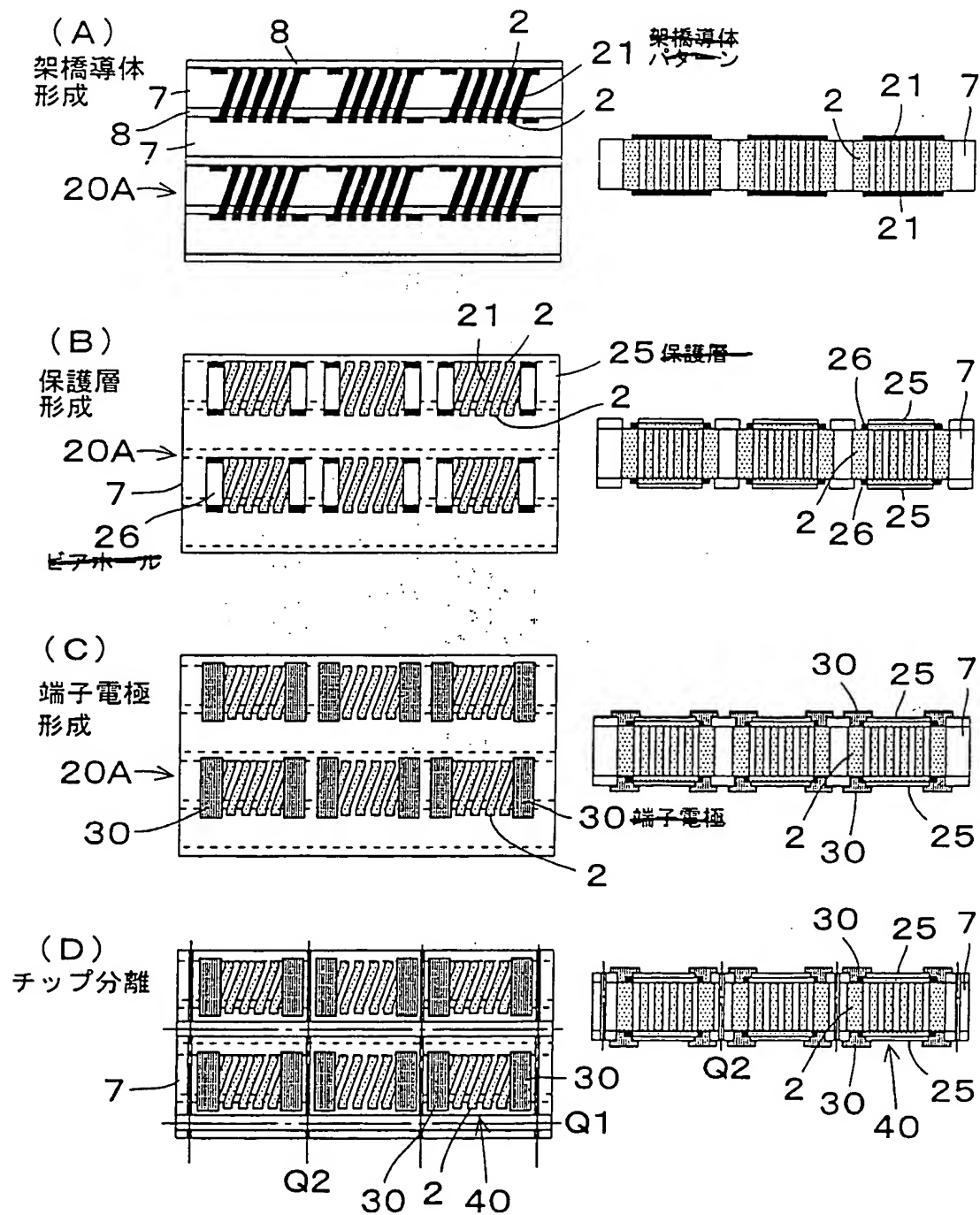
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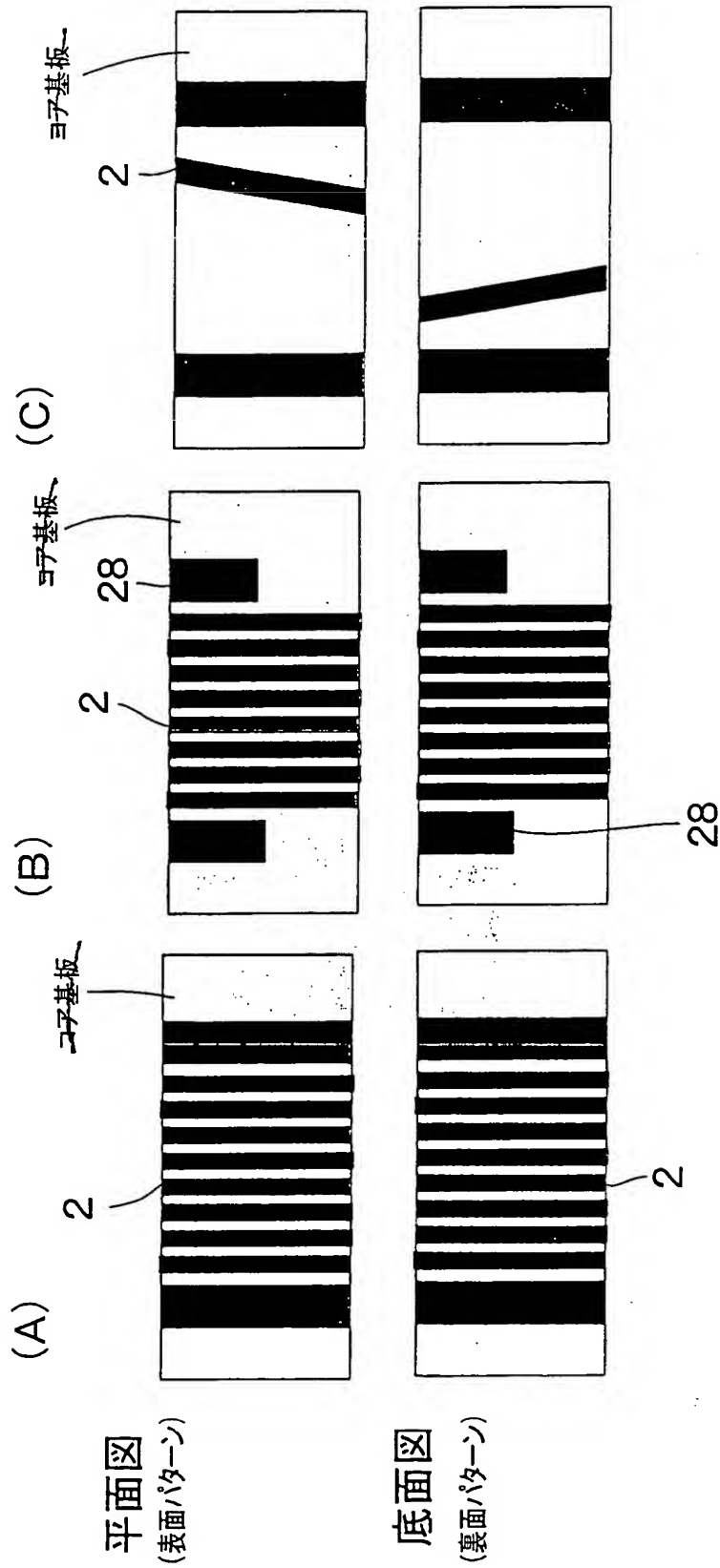


【図8】

断面図

平面図





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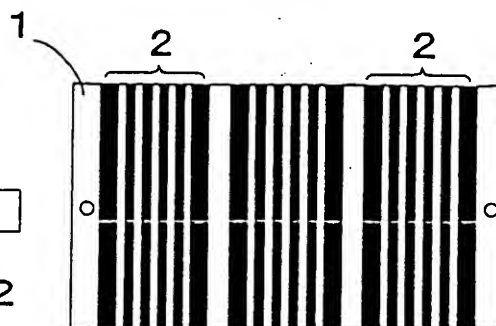
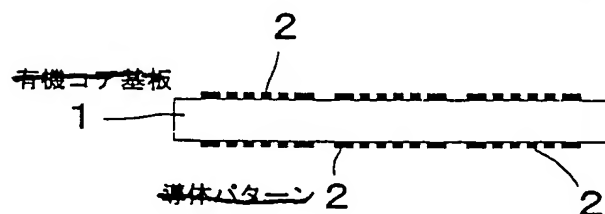
10/E

【図10】

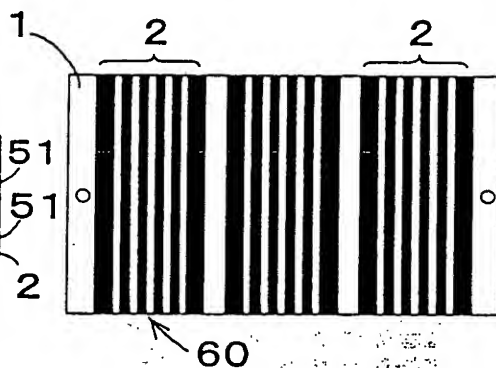
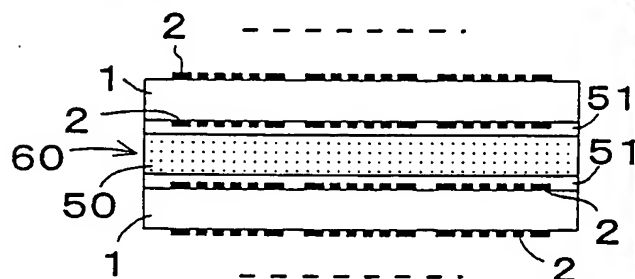
断面図

平面図

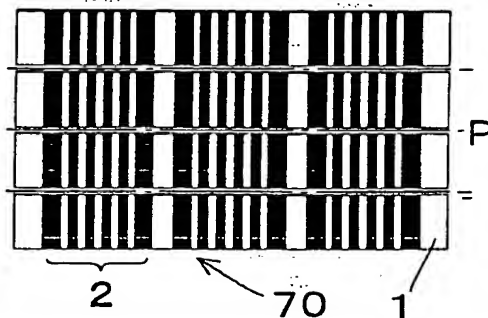
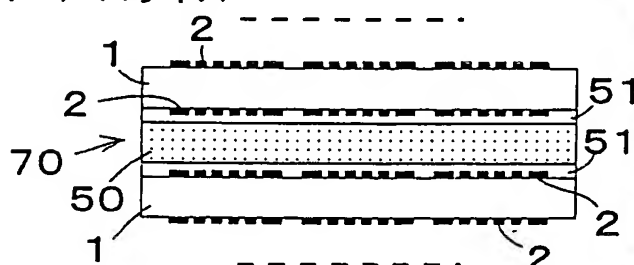
(A) 带状導体作製



(B) 積層



(C) スライス



(D) 架橋導体形成

